

BIPOLAR ANALOG INTEGRATED CIRCUIT

μ PC8204TK

VARIABLE GAIN AMPLIFIER FOR TRANSMITTER AGC

DESCRIPTION

The μ PC8204TK is a silicon monolithic integrated circuit designed as variable gain amplifier. The package is 6-pin lead-less minimold suitable for surface mount.

This IC is manufactured using our 30 GHz f_{max} UHS0 (Ultra High Speed Process) silicon bipolar process.

This IC is as same circuit current as conventional μ PC8119T and μ PC8120T, but operates at higher frequency and wider gain control range.

FEATURES

- Gain control range : GCR = 40 dB TYP. @ f = 1.9 GHz
: GCR = 40 dB TYP. @ f = 2.4 GHz
- Maximum power gain : G_{PMAX} = 14.5 dB TYP. @ f = 1.9 GHz
: G_{PMAX} = 14.0 dB TYP. @ f = 2.4 GHz
- Operating frequency : f = 0.8 to 2.5 GHz
- Supply voltage : V_{CC} = 2.7 to 3.3 V
- High-density surface mounting : 6-pin lead-less minimold package

APPLICATION

- 0.8 to 2.5 GHz transmitter/receiver system (PHS, WLAN and so on)

ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
μ PC8204TK-E2	6-pin lead-less minimold (1511)	6E	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pin 1, 6 face the perforation side of the tape • Qty 5 kpcs/reel

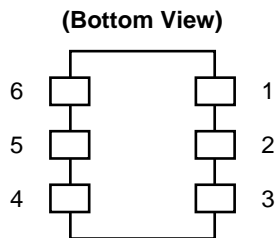
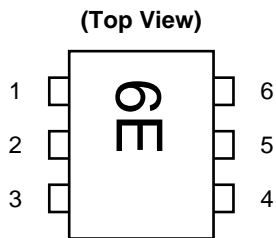
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PC8204TK

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PIN CONNECTIONS



Pin No.	Pin Name
1	INPUT
2	GND
3	GND
4	OUTPUT
5	V _{CC}
6	V _{AGC}

VARIABLE GAIN AMPLIFIER PRODUCT LINE-UP

Parameter Part No.	I _{CC} (mA)	0.95 GHz output port matching frequency			1.44 GHz output port matching frequency			1.9 GHz output port matching frequency			2.4 GHz output port matching frequency		
		G _{PMAX} (dB)	GCR (dB)	NF (dB)	G _{PMAX} (dB)	GCR (dB)	NF (dB)	G _{PMAX} (dB)	GCR (dB)	NF (dB)	G _{PMAX} (dB)	GCR (dB)	NF (dB)
μPC8204TK	11.5	-	-	-	-	-	-	14.5	40	7.5	14.0	40	7.5
μPC8119T	11.0	12.5	50	8.5	13.0	45	7.5	(12.5)	(22)	(7.2)	-	-	-
μPC8120T	11.0	13.0	50	9.0	13.5	45	7.5	(13.0)	(22)	(7.3)	-	-	-

- Remarks 1.** Typical performance. Please refer to **ELECTRICAL CHARACTERISTICS** in detail. (): reference.
2. To know the associated product, please refer to each latest data sheet.

PIN EXPLANATION

Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V) <small>Note</small>	Function and Applications	Internal Equivalent Circuit
1	INPUT	–	1.2	RF input pin. This pin should be coupled with capacitor (example 100 pF) for DC cut. Input return loss can be improved with external impedance matching circuit.	
2 3	GND	0	–	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. Ground pins must be connected together with wide ground pattern to decrease impedance difference.	
4	OUTPUT	Voltage as same as V _{CC} through external inductor	–	RF output pin. This pin is designed as open collector of high impedance. This pin must be externally equipped with matching circuits.	
5	V _{CC}	2.7 to 3.3	–	Supply voltage pin. This pin must be equipped with bypass capacitor (example 1 000 pF) to minimize its RF impedance.	
6	V _{AGC}	0 to 3.3	–	Gain control pin.	

Note Pin voltage is measured at V_{CC} = 3.0 V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	V _{CC}	T _A = +25°C, Pin 4, 5	3.6	V
Total Circuit Current	I _{CC}	T _A = +25°C	30	mA
Gain Control Voltage	V _{AGC}	T _A = +25°C	3.6	V
Power Dissipation	P _D	T _A = +85°C Note	203	mW
Operating Ambient Temperature	T _A		-40 to +85	°C
Storage Temperature	T _{stg}		-55 to +150	°C
Input Power	P _{in}		+5	dBm

Note Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
Supply Voltage	V _{CC}	2.7	3.0	3.3	V	Same voltage should be applied to pin 4 and pin 5.
Operating Ambient Temperature	T _A	-40	+25	+85	°C	
Operating Frequency Range	f _{in}	0.8	-	2.5	GHz	With external output-matching
Gain Control Voltage	V _{AGC}	0	-	3.3	V	

ELECTRICAL CHARACTERISTICS (T_A = +25°C, V_{CC} = V_{out} = 3.0 V, Z_s = Z_L = 50 Ω, external matched output port, unless otherwise specified)

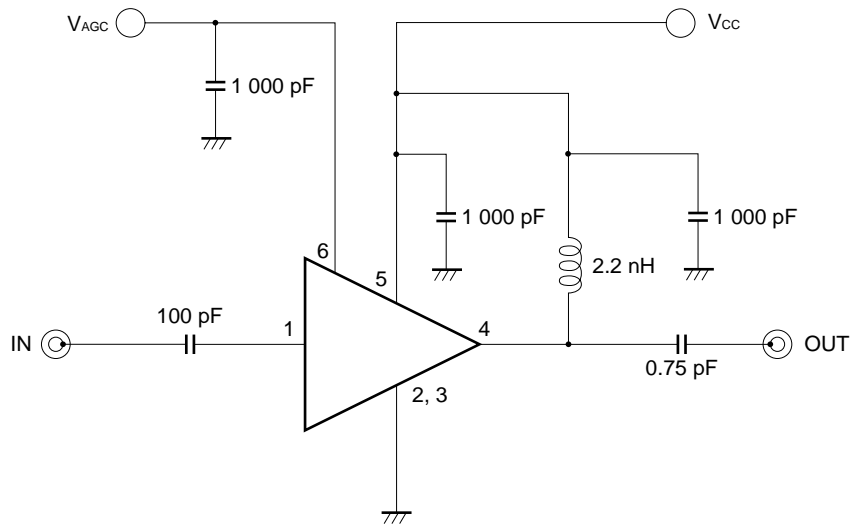
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	I _{CC}	No signal	8.5	11.5	15.0	mA
Maximum Power Gain	G _{PMAX}	f = 1.9 GHz, P _{in} = -20 dBm	11.5	14.5	17.5	dB
		f = 2.4 GHz, P _{in} = -20 dBm	11.0	14.0	17.0	
Gain Control Range ^{Note}	GCR	f = 1.9 GHz, P _{in} = -20 dBm	35	40	-	dB
		f = 2.4 GHz, P _{in} = -20 dBm	35	40	-	
Gain 1 dB Compression Output Power	P _{O(1 dB)}	f = 1.9 GHz, G _{PMAX}	+2.0	+5.0	-	dBm
		f = 2.4 GHz, G _{PMAX}	+2.0	+5.0	-	
Input Return Loss	RL _{in}	f = 1.9 GHz, G _{PMAX}	8	11	-	dB
		f = 2.4 GHz, G _{PMAX}	9	13	-	
Isolation	ISL	f = 1.9 GHz, G _{PMAX}	25	30	-	dB
		f = 2.4 GHz, G _{PMAX}	25	30	-	
Noise Figure	NF	f = 1.9 GHz, G _{PMAX}	-	7.5	10.0	dB
		f = 2.4 GHz, G _{PMAX}	-	7.5	10.0	

Note Gain control range GCR specification : GCR = G_{PMAX} - G_{PMIN} (dB)

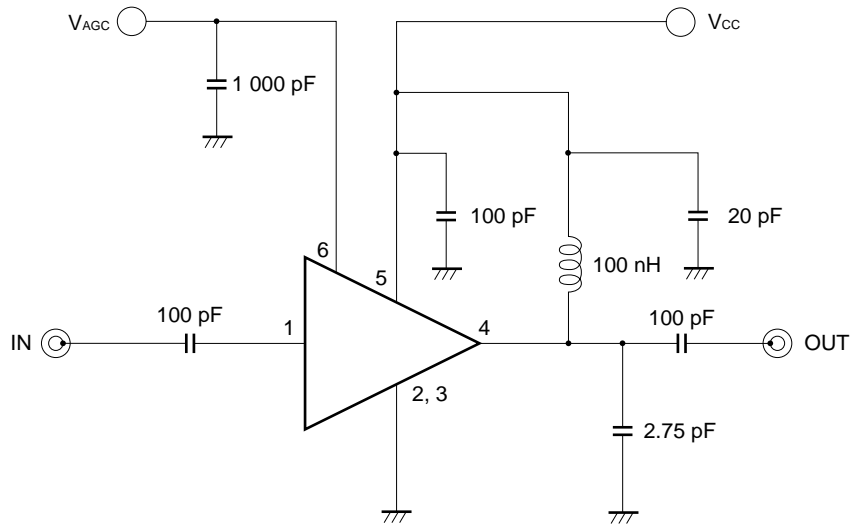
Conditions G_{PMAX}@V_{AGC} = V_{CC}, G_{PMIN}@V_{AGC} = 0 V

TEST CIRCUITS

<1> $f = 1.9 \text{ GHz}$

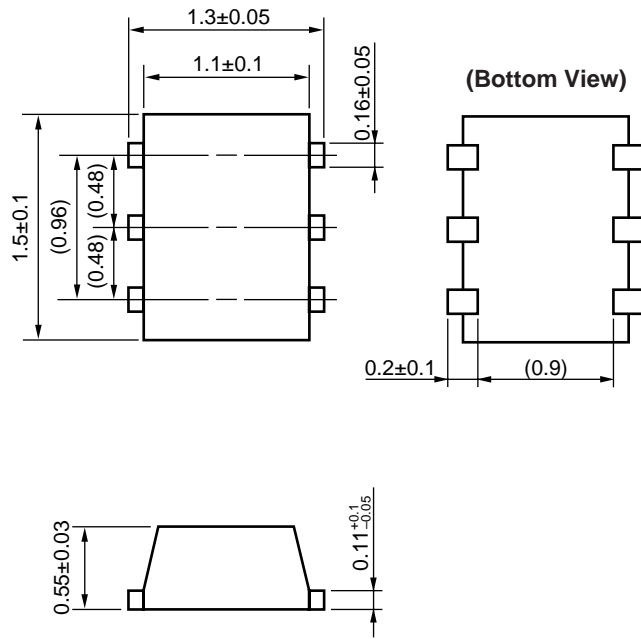


<2> $f = 2.4 \text{ GHz}$



PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511) (UNIT: mm)



Remark (): reference

NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as wide as possible to minimize ground impedance (to prevent undesired oscillation).
All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to the Vcc pin.
- (4) Impedance matching circuit must be each externally attached to input and output ports.
- (5) The DC capacitor must be attached to input pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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